

MATERIAL DATA SHEET



SMD Diodes Specialist

Material #	CDBM Series (Mini-SMA)		
Product Line	SMD Schottky Diode		
Date	2009/10/5		
Rev. date	E		

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	Lead Frame	Alloy	15.6	Copper (Cu)	7440-50-8	99.6	59.01%	
				Iron (Fe)	7439-89-6	0.4		
2	Chip	Schottky Chip	0.1092	Silicon (Si)	7440-21-3	98	0.41%	
				Gold (Au)	7440-57-5	2		
3	Solder	Pb/Sn/Ag	0.1312	Tin (Sn)	7440-31-5	5	0.50%	
				Lead (Pb)	7439-92-1	92.5		
				Silver (Ag)	7440-22-4	2.5		
4	Molding Compound	Epoxy	10.47	Silica (Fused)	7631-86-0	80.0~90.0	39.61%	
				Epoxy resin	29690-82-2	5		
				Phenolic Resin	9003-35-4	5		
				Antimony Oxide	1309-64-4	<1.0		
				Brominated Compound	---	<1.0		
5	Plating	Tin	0.125	Tin (Sn)	7440-31-5	100	0.473%	
Total weight			26.4354					